

Fliptop Cases

APPLICATIONS

This distinctive wedge-shaped housing is specifically designed for portable instrument applications. The case offers a robust construction able to withstand both internal and external environments. Interconnection and controls are easily catered for in the base section with the inclusion of an aluminium cover plate. The fliptop case therefore offers an economical packaging solution to the ever growing number of portable electronic instrument applications.

CONSTRUCTION

The case consists of a moulding which includes the base section and flip over lid. The two halves are connected by an integral hinge section and the case is opened and securely shut using a robust snap together clip, moulded to the front of the lid.

The base includes six moulded bosses for horizontal PCB mounting, the largest case being suitable for housing a single Eurocard 100 x 160mm. The kit includes six self-tapping screws for PCB mounting.

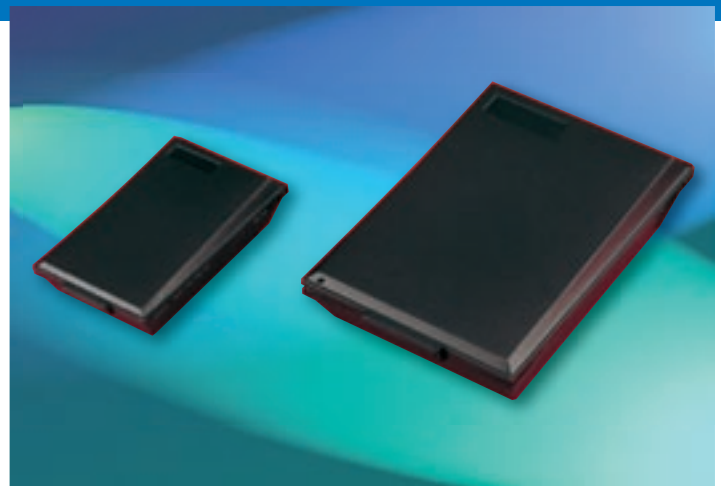
An aluminium cover plate is assembled to the base section. The plate is retained by two clips at the rear and secured firmly by a screw fixing at the front.

Contents of kit

Description	Material/Finish
Case	Polypropylene
Flame class rating	Non flame retardant Black
Temp. range	-20°C to 65°C
Cover plate	Etched and anodised aluminium Size 1 1mm thickness, Size 2 1,6mm thickness
Hinge life	>10,000 operations within temp range

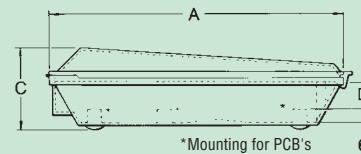
Ordering information

Size	Dimensions					Order code
	A	B	C	D	E	
1	130	75	34	11,5	6	75-3018
2	196	127	51	21,5	10	75-3019

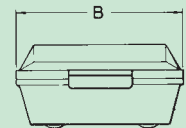


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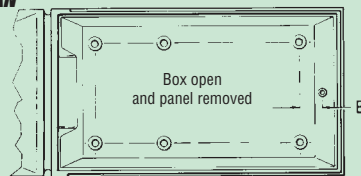
SECTION



FRONT

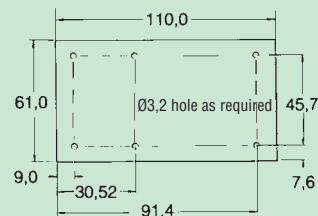


PLAN



MAXIMUM CIRCUIT BOARD SIZES

SIZE 1



SIZE 2

